

Fully Integrated Analog Front-End Dual Receiver Base Unit for 27-MHz Wireless Mouse and Keyboard Systems

FEATURES

- 23 Discrete Components Intgrated into One Chip
 - Only External Components are Bypass and Filter Capacitors, and One Crystal
- RF Tuner, Mixer, Transistors, Passives, Coils, and Ceramic Filter Functionality All on One Chip
- Integrated Phase Locked Loop
- 8 User-Selectable Frequencies
 - Each Channel (Mouse and Keyboard) Can Independently Select Any of the Available Frequencies
- Internally Generated 6-MHz Clock to Drive USB Microcontroller

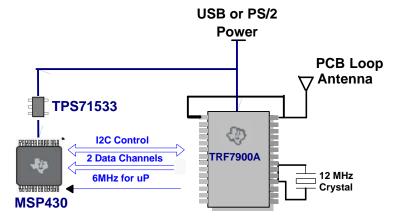
- High Data Throughput Rate
 - 5-kHz Square Wave Simultaneously per Channel
 - 10 kbps Miller Encoded Data
- I²C Control Interface
- Received Signal Strength Indicator
- 5-V Supply
- Available in 28-Pin TSSOP (PW) Pacakge

APPLICATIONS

- 27-MHz Wireless Mouse and Keyboard Systems
- Human Interface Devices
- Wireless Control
- Remote Control Toys
- Wireless Headset
- Remote instrumentation

DESCRIPTION

The TRF7900A is a dual integrated RF transceiver designed for human-interface devices (HID). Operating at 27 MHz, it integrates multiple components (PLL, RF mixer, simulated SAW filter, tuning circuit, and miscellaneous passive components) to provide frequency selection from 8 discrete channels. This integration lowers component, manufacturing and system costs.



The TRF7900A simplifies system design by reducing system component count and manual circuit tuning. By integrating the PLL, SAW filter, and RF mixer, the TRF7900A eliminates the manual tuning of RLC circuits required in traditional implementations.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



The receiver also generates 8 frequencies that can be programmatically selected via the I²C interface bus for both the mouse channel and/or the keyboard channel. Another 6-MHz clock is internally generated to clock the USB microcontroller; this enables a single crystal to be used to supply the clock needs for the receiver channels and the microcontroller.

The optimized receiver design enables simultaneous reception on both parallel channels up to 5 kHz (10 kbps Miller encoding) per channel. A receive strength signal indicator register can be read via the I²C bus to determine the signal strength. Correlating the RSSI reading to the packet error rate enables the controller to diagnose the signal and understand the user condition.

ORDERING INFORMATION

PACKAGED DEVICES	PACKAGE TYPE	TRANSPORT MEDIA, QUANTITY	
TRF7900APW	TSSOP - 28	Rails, 50	
TRF7900APWR	TSSOP - 28	Tape and Reel, 2000	

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)

		VALUE	UNIT ⁽¹⁾
V _{S-} to V _{S+}	Supply voltage	5.5	V
V _I	Input voltage	±V _S ± 0.5	V
V _{ID}	Differential input voltage	±2	V
	Continuous power dissipation	See Dissipation Rating Table	
T _J	Maximum junction temperature, any condition (2)	150	°C
T_J	Maximum junction temperature, continuous operation, long term reliability(3)	125	°C
T _{stg}	Storage temperature range	-65 to 150	°C
	Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	300	°C
	ESD ratings: Human Body Model	4000	V
	ESD ratings: Charged Device Model	1500	V
	ESD ratings: Machine Model	200	٧

⁽¹⁾ The absolute maximum ratings under any condition is limited by the constraints of the silicon process. Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

DISSIPATION RATINGS

PACKAGE	0	θ _{JA} (1)	POWER RATING ⁽²⁾	
PACKAGE	A1C		T _A ≤ 25°C	T _A = 85°C
PW (28)	13.7	56.5	1.77 W	708 mW

⁽¹⁾ This data was taken using the JEDEC standard high-K test PCB.

⁽²⁾ The maximum junction temperature for continuous operation is limited by package constraints. Operation above this temperature may result in reduced reliability and/or lifetime of the device.

⁽²⁾ Power rating is determined with a junction temperature of 125°C. This is the point where distortion starts to substantially increase. Thermal management of the final PCB should strive to keep the junction temperature at or below 125°C for best performance and long term reliability.



RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM MAX	UNIT
V_{S-} to V_{S+}	Suppy voltage, analog	4.0	5.5	V

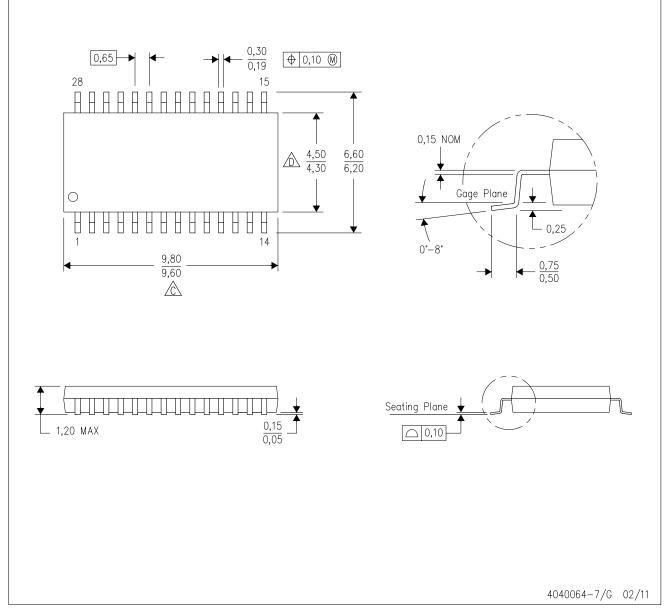
ELECTRICAL CHARACTERISTICS

 $V_S = 5 \text{ V}, T_A = 25^{\circ}\text{C}$ (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN TYP	MAX	UNIT
Io	Output current		100	100	mA
RF Spe	cifications				
	Precision of required external 12-MHz crystal			50	ppm
	Channel spacing		50		kHz
			26.995		MHz
			27.045		MHz
			27.095		MHz
			27.145		MHz
	Communication spacing Antenna Input Resistance		27.195		MHz
			27.295		MHz
		Optional channel	27.245		MHz
		Optional channel	26.945		MHz
		DC Differential	<100		kΩ
		27 MHz	5		kΩ
R _O	Output resistance, Out_1 and Out_2		1.2		kΩ

PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom **Amplifiers** amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers <u>microcontroller.ti.com</u> Video and Imaging <u>www.ti.com/video</u>

RFID <u>www.ti-rfid.com</u>

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов:
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001:
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина,

дом 2, корпус 4, литера А.